

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	507	polishing adj pad and pressure with center	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/02 15:56
S3	107	S2 and (wafer semiconductor microelectronic)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/02 15:57
S4	2	"20040266193".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/02 16:16
S5	23	polishing adj pad and pressure with center with (more higher) and bow\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/02 16:33
S6	2	polishing adj pad same pressure with center with (more higher) same bow\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/02 17:08
S8	91	("1739657" "1758682" "2540602" "3328273" "4140598" "4430173" "4948474" "4954142" "4975159" "5084071" "5256565" "5354490" "5516412" "5543032" "5558568" "5681215" "5755859" "5762544" "5770095" "5773364" "5793272" "5795215" "5807165" "5840629" "5858813" "5884990" "5897375" "5911619" "5922091" "5930669" "5933753" "5954997" "5985123" "6004880" "6027631" "6063506" "6066030" "6071388" "6074544" "6103085" "6132578" "6136163" "6176992" "6217426").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/02 17:58
S10	2	"200026443"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/02 18:01
S9	80	"4324330" "706857" "9827585" "0026443"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/02 18:01

S11	0	WSID same pressure with central with (more higher) same bow\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/02 18:17
S12	1	WSID and pressure with center with (more higher)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/02 18:18
S14	114	ecmp and support	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/02 18:23
S13	195	ecmp	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/02 18:23
S2	110	polishing adj pad and pressure with center with (more higher)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/02 18:23
S16	0	ecmp and semitool	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/02 18:27
S15	7	ecmp and support and nutool	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/02 18:27
S17	59	ecmp and applied adj materials	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/02 18:29
S18	23	ecmp and international	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/02 18:30
S20	2	"6413388".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/02 18:40

S19	25	ecmp and uzoh	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/02 18:40
S21	39	("3328273"   "4430173"   "4948474"   "4954142"   "4975159"   "5084071"   "5256565"   "5354490"   "5516412"   "5543032"   "5681215"   "5755859"   "5762544"   "5770095"   "5773364"   "5793272"   "5795215"   "5807165"   "5840629"   "5858813"   "5884990"   "5897375"   "5911619"   "5922091"   "5930669"   "5933753"   "5954997"   "5985123"   "6004880"   "6027631"   "6063506"   "6066030"   "6071388"   "6074544"   "6103085"   "6132578"   "6136163"   "6176992").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/06/02 18:48
S23	1	"20020130034".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2005/06/02 18:55
S22	110	(ecmp ecmd) and (filter membrane)	US-PGPUB; USPAT; USOCR	OR	ON	2005/06/02 18:55
S24	47	("5931719").URPN.	USPAT	OR	ON	2005/06/02 19:25
S25	17	("1212628"   "4270316"   "4313284"   "4918869"   "4930264"   "5191738"   "5423716"   "5441444"   "5541442"   "5584746"   "5597346"   "5605487"   "5605488"   "5762539"   "5762546"   "5800248").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/06/02 19:48
S26	19	451/41.ccls. and air adj bladder	US-PGPUB; USPAT; USOCR	OR	ON	2005/06/02 19:52
S27	2856	(support platen) same (abrasive pad) same pressure with (center central periphery peripheral)	US-PGPUB; USPAT; USOCR	OR	ON	2005/06/02 19:53
S28	84	(support platen) same (abrasive pad) same pressure with (center central periphery peripheral) and (ecmp cmp ecmd cmd)	US-PGPUB; USPAT; USOCR	OR	ON	2005/06/02 20:04
S30	1	compressible adj pad same porous adj membrane	US-PGPUB; USPAT; USOCR	OR	ON	2005/06/02 20:15

S29	1	(support platen) same (abrasive pad) same pressure with (center central periphery peripheral) and (ecm)	US-PGPUB; USPAT; USOCR	OR	ON	2005/06/02 20:15
S31	2	compressible adj pad same porous with membrane	US-PGPUB; USPAT; USOCR	OR	ON	2005/06/02 20:16
S35	245	S34 and (pad abrasive)	US-PGPUB; USPAT; USOCR	OR	ON	2005/06/02 20:17
S34	462	(electrochemical adj mechanical)	US-PGPUB; USPAT; USOCR	OR	ON	2005/06/02 20:17
S33	8493	ecmp ecm ecmd (electrochemical adj mechanical)	US-PGPUB; USPAT; USOCR	OR	ON	2005/06/02 20:17
S32	2	polishing adj pad same porous with membrane	US-PGPUB; USPAT; USOCR	OR	ON	2005/06/02 20:17
S36	2	S34 and (pad abrasive) and porous adj membrane	US-PGPUB; USPAT; USOCR	OR	ON	2005/06/02 20:18
L6	11	L4 and porous with membrane	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/07 14:35
L12	59	electro adj chemical adj mechanical with (plating deposit\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/07 15:22
L11	2	"6176992".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/07 15:22
L5	79	L4 and porous	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/07 15:22
L4	193	electrochemical adj mechanical with (plating deposit\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/07 15:22

L14	0	L12 and porous with membrane	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/07 15:23
L13	20	L12 and porous	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/07 15:23
L17	224	4 or 12	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/07 15:24
L16	23	4 or 12	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/07 15:24
L21	296	L19 and porous	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/07 15:26
L20	6	L19 and porous	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/07 15:26
L18	6	L15 and porous	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/07 15:26
L15	214	(electrochemical (electro adj chemical)) with mechanical with (plating deposit\$3 process\$3)	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/07 15:26
L22	53	L19 and porous with (member membrane diffuser)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/07 15:27
L23	2	"6261433".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/07 15:28
L19	1229	(electrochemical (electro adj chemical)) with mechanical with (plating deposit\$3 process\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/07 15:34
L25	1	"6004880".PN.	USPAT; USOCR	OR	ON	2005/06/07 15:36



L24	537	(electrochemical (electro adj chemical)) with mechanical with (plating deposit\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/07 15:42
L27	160	basol near2 bulent	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/07 15:46
L26	16	jeffrey near2 bogart	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/07 15:46
L28	10	27 and (bow bowing flex flexing)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/07 15:47
S7	4	polishing adj pad same pressure with central with (more higher) same bow\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/07 15:56
L29	50	27 and (bow bowing flex flexing flexible)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/07 15:56
L31	6089	CMP and side adj wall	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/07 15:58
L30	5	polishing adj pad same pressure with (uniform even evenness) same side adj wall	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/07 15:58
L32	199	CMP and side adj wall and "451". clas.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/07 16:05
L35	29528	uniform adj pressure smae wall and CMP	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/07 16:19

L34	389	uniform adj pressure and CMP	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/07 16:19
L33	37	CMP and side adj wall same pressure and "451".clas.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/07 16:19
L36	8	uniform adj pressure same wall and CMP	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/07 16:26
L37	2	extendable adj side adj wall same pressure	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/07 16:28
L38	167	compressible with side adj wall same pressure	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/07 16:29
L39	6	compressible with side adj wall same pressure with (uniform even)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/07 16:42
L40	3402923	pressure near2 (uniform even) with (container tank vessel) with wall with (flexible compressible expandable)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/07 16:43
L42	333	239/33.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/07 16:48
L43	0	pressure near2 (uniform even) with (container tank vessel) with wall with (corrugat\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/07 16:53
L44	0	pressure near2 (uniform even) with (container tank vessel) with wall with (corrugat\$5)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/07 16:55

L46	0	pressure near2 (uniform even) with (container tank vessel) with wall with (ridge)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/07 16:56
L45	0	pressure near2 (uniform even) with (container tank vessel) with wall with (accordion)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/07 16:56
L50	594	pressure near2 (uniform even) with (container tank vessel chamber) with wall	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/07 16:57
L49	246	pressure near2 (uniform even) with (container tank vessel) with wall	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/07 16:57
L48	0	pressure near2 (uniform even) with (container tank vessel chamber) with wall with (ridge\$2)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/07 16:57
L47	0	pressure near2 (uniform even) with (container tank vessel) with wall with (ridge\$2)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/07 16:57
L41	15	pressure near2 (uniform even) with (container tank vessel) with wall with (flexible compressible expandable)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/07 16:57
L51	14	pressure near2 (uniform even) with (chamber) with wall with (flexible compressible expandable)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/07 17:02
L52	134	pressure near2 (uniform even regular equal constant) with (container tank vessel chamber) with wall with (flexible compressible expandable corrugat\$5 accordion)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/07 17:16
L53	26	pressure near2 (uniform even regular equal constant) with (container tank vessel chamber) with wall with (bellows)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/07 17:19



L56	77	baffle with constant adj pressure	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/07 17:40
L55	7	54 not 53	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/07 17:40
L57	33	(force pressure) near2 (uniform even evenness regular equal constant) with (container tank vessel chamber) with wall with (bellows)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/07 17:48
L54	33	(force pressure) near2 (uniform even regular equal constant) with (container tank vessel chamber) with wall with (bellows)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/07 17:48
L58	188	(force pressure) near2 (uniform even evenness regular equal constant) with (container tank vessel chamber) with wall with (bellows baffles ridge\$2 flexible compressible expandable corrugat\$5 accordion)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/07 17:53
L59	682	bellows and "204".clas.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/07 17:54
L60	410	bellows and "204".clas. and pump	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/07 18:21

L69	39	("3328273"   "4430173"   "4948474"   "4954142"   "4975159"   "5084071"   "5256565"   "5354490"   "5516412"   "5543032"   "5681215"   "5755859"   "5762544"   "5770095"   "5773364"   "5793272"   "5795215"   "5807165"   "5840629"   "5858813"   "5884990"   "5897375"   "5911619"   "5922091"   "5930669"   "5933753"   "5954997"   "5985123"   "6004880"   "6027631"   "6063506"   "6066030"   "6071388"   "6074544"   "6103085"   "6132578"   "6136163"   "6176992").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/06/07 18:58
L70	89	("5807165").URPN.	USPAT	OR	ON	2005/06/07 19:11
L72	4	ECMP and cup	USPAT	OR	ON	2005/06/07 19:12
L71	515	CMP and cup	USPAT	OR	ON	2005/06/07 19:14
L74	2156	CMP and (semiconductor wafer microelectronic) and "451".clas.	USPAT	OR	ON	2005/06/07 19:22
L73	149	CMP and cup and "451".clas.	USPAT	OR	ON	2005/06/07 19:22
L76	26	L75 not L73	USPAT	OR	ON	2005/06/07 19:23
L75	172	L74 and (cup bowl)	USPAT	OR	ON	2005/06/07 19:23
L77	7	("4490948"   "5531635"   "5554064"   "5569062"   "5643067"   "5658185"   "5679063").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/06/07 19:28
L78	28	("5658185").URPN.	USPAT	OR	ON	2005/06/07 19:47
L79	1	"5876271".PN.	USPAT; USOCR	OR	ON	2005/06/07 19:49